

Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

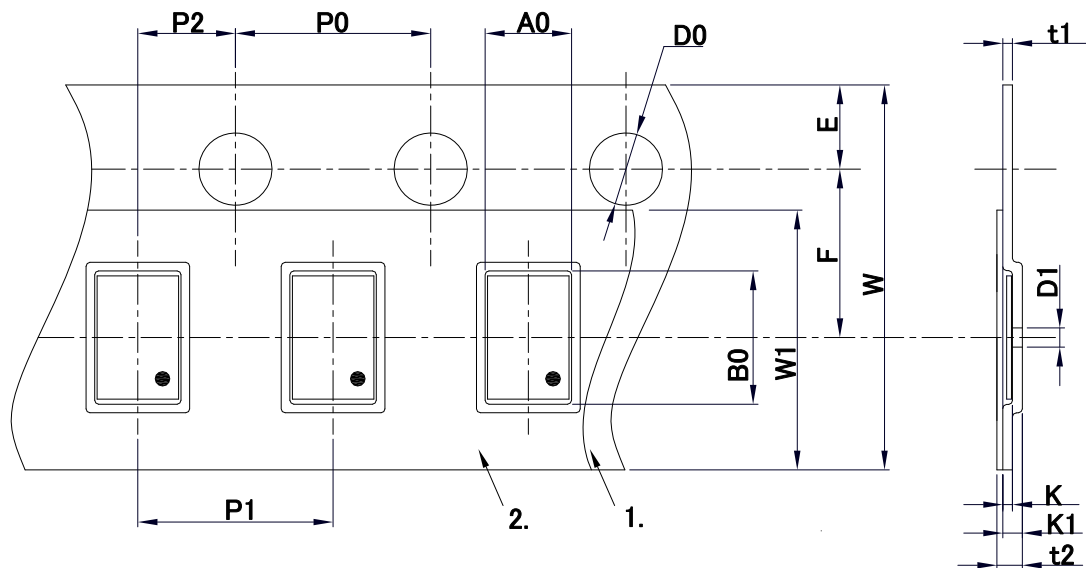
1. Taping quantity

Part Number FC□□□□□□□L : The standard quantity shall be 10 000 pcs / reel.

Part Number FC□□□□□□□L1 : The standard quantity shall be 1 000 pcs / reel.

2. Taping form and dimensions

Unit:mm



1. Carrier tape

2. Cover tape

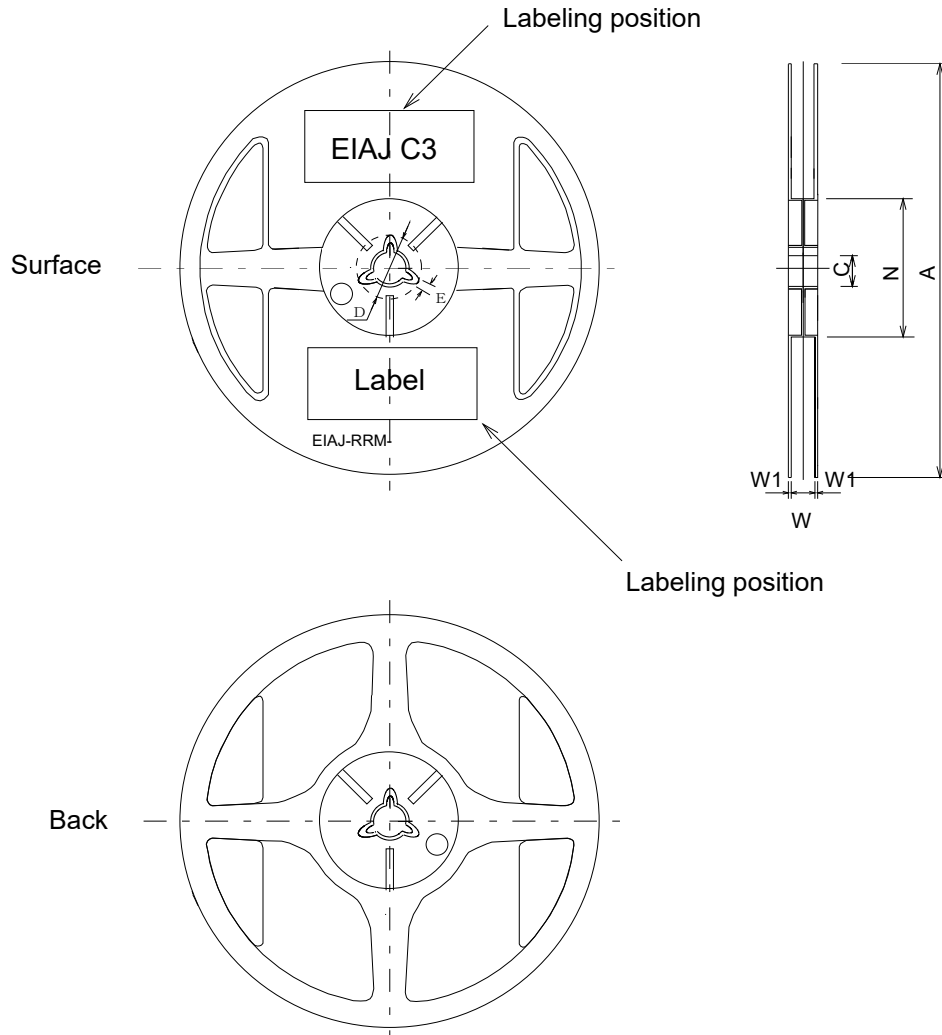
Item	Symbol	Dimensions	Remarks	
Dented square hole for product insertion	Length	A0	1.771±0.050	
	Width	B0	2.771±0.050	
	Depth	K	0.20±0.03/-0.02	
	Pitch	P1	4.00±0.10	
Sprocket hole	Diameter	D0	1.50±0.10/-0.00	
	Pitch	P0	4.00±0.10	Accumulated error 200±0.30/50 pitches
	Position	E	1.75±0.10	
Embossing hole	Diameter	D1	0.40±0.05	
Center-to-center distance	Longitudinal	P2	2.00±0.05	
	Traverse	F	3.50±0.05	
Cover tape	Width	W1	5.40±0.10	
Carrier tape	Width	W	8.00±0.20	
	Thickness	t1	0.20±0.05	
Hole outer depth	K1	0.40±0.10		
Total thickness	t2	0.45±0.20		

Note : 1) Radius at each corner shall be 0.08R or less.

Taping Specifications
MLGA006-W-1727-RB

3. Reel and dimensions

Unit:mm



Item		Symbol	Dimensions	Remarks
Flange	Diameter	A	180+0/-3	
	Thickness	W1	1.2	
	Distance between flanges	W	9.0±0.3	
Hub	Outer diameter	N	60+1/-0	
	Spindle hole diameter	C	13.0±0.2	
	Keyway			
	Width	E	2.0±0.5	
	Depth	D	21.0±0.8	
Indication of the type		Mark on one side of flange Indicate type name, quantity and serial No. etc.		

Request for your special attention and precautions in using the technical information and semiconductors described in this book

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